



## **Product Summary**

BV <sub>DSS</sub>	RDS(ON) Max	I <sub>D Max</sub> T <sub>A</sub> = +25°С
20\/	25mΩ @ VGs = -10V	-8.5A
-30V	38mΩ @ V <sub>GS</sub> = -4.5V	-6.9A

### Description

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

## Applications

- General-purpose interfacing switches
- Power-management functions

### **30V P-CHANNEL ENHANCEMENT MODE MOSFET**

### Features

- Low Gate Threshold Voltage
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

## **Mechanical Data**

- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)

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Internal Schematic

• Weight: 0.0065 grams (Approximate)

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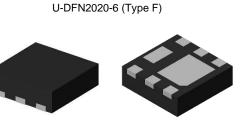
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Top View

Bottom View

## Ordering Information (Note 4)

Orderable Part Number	Marking	Baakaga	Packing			
	Marking	Package	Qty.	Carrier		
DMP3027LFDF-7	7F	U-DFN2020-6 (Type F)	3000	Tape & Reel		
DMP3027LFDF-13	7F	U-DFN2020-6 (Type F)	10,000	Tape & Reel		

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

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Pin Out

**Bottom View** 

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3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**

Notes:

Date Code Key			•	7F X	YW Y = W		Code Mark 4 = 2024) k: a = Wee	king		Neek 52 and	1 53)	
Year	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034
Code	3	4	5	6	7	8	9	0	1	2	3	4
Week	1-26				27-52			53				
Code	A-Z				a-z			Z				
Internal Code	Sur	n 🗌	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		U		V	1	N	Х		Y		Z



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Characteristic					
Drain-Source Voltage	Vdss	-30	V			
Gate-Source Voltage	Vgss	VGSS ±20				
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-8.5 -6.8	A	
Maximum Body Diode Forward Current (Note 6)	-		Is	-2.8	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	Ідм	-49	А			
Avalanche Current (Note 9) L = 0.1mH	las	-25	А			
Avalanche Energy (Note 9) L = 0.1mH		Eas	32	mJ		

## **Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	86.1	°C/W
Total Power Dissipation (Note 6)		PD	2.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	45.8	°C/W
Thermal Resistance, Junction to Case (Note 6)		R <sub>θJC</sub>	2.3	C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

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	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	1			1		
Drain-Source Breakdown Voltage	BVDSS	-30	—	_	V	Vgs = 0, Id = -250µA
Zero Gate Voltage Drain Current	IDSS			-1	μA	$V_{DS} = -30V, V_{GS} = 0$
Gate-Source Leakage	lgss	—	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	Vgs(th)	-1.2		-2.4	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$
Static Drain-Source On-Resistance	Deserve	_	17.5	25	mΩ	$V_{GS} = -10V, I_D = -7A$
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)		30.3	38	11122	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -6.2A
Diode Forward Voltage	Vsd	_	-0.7	-1.2	V	V <sub>GS</sub> = 0, I <sub>S</sub> = -2.1A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	1142	_		
Output Capacitance	Coss	_	145	_	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	116	_		I = 1.000112
Gate Resistance	Rg	_	4.8	_	Ω	V <sub>DS</sub> = 0, V <sub>GS</sub> = 0, f = 1.0MHz
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	—	21.8	_		
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	11.2	_		
Gate-Source Charge	Qgs	_	3.3	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -7A
Gate-Drain Charge	Q <sub>gd</sub>	—	4.6	_		
Turn-On Delay Time	tD(on)	_	5.3			
Turn-On Rise Time	tr	_	27.9	_	ns	$V_{GS} = -10V$ , $V_{DD} = -15V$ , $R_{GEN} = 6\Omega$ ,
Turn-Off Delay Time	tD(off)	_	41.17	_	115	I <sub>D</sub> = -7A
Turn-Off Fall Time	t <sub>f</sub>	_	30.9	_		

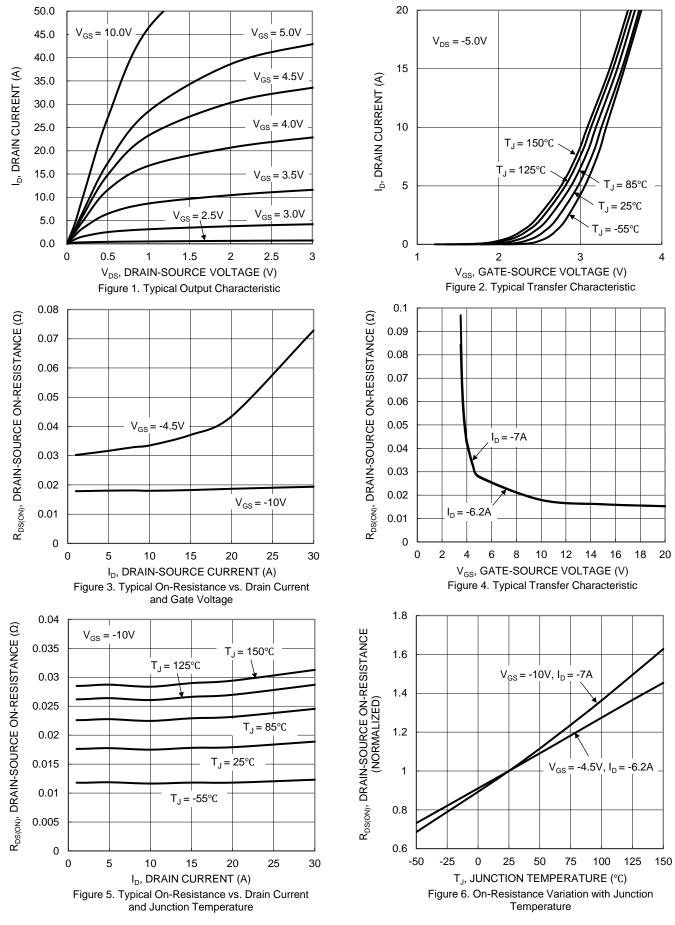
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

9.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25^{\circ}C$ .

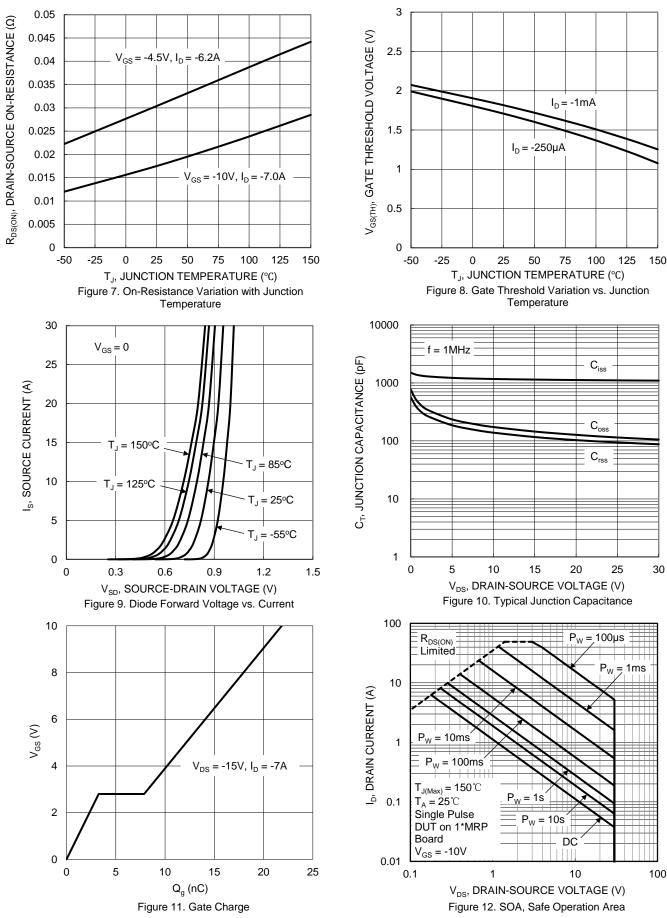


## DMP3027LFDF



DMP3027LFDF Document number: DS45461 Rev. 3 - 2

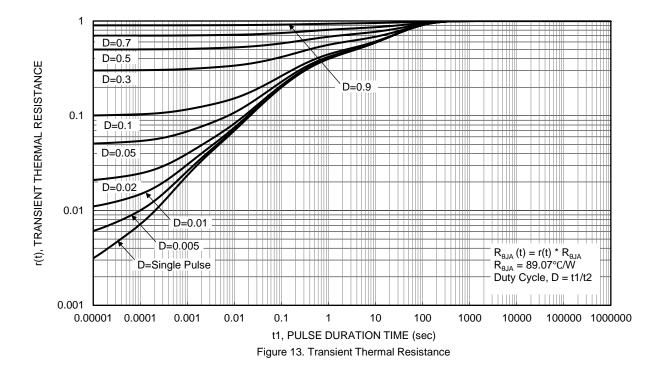




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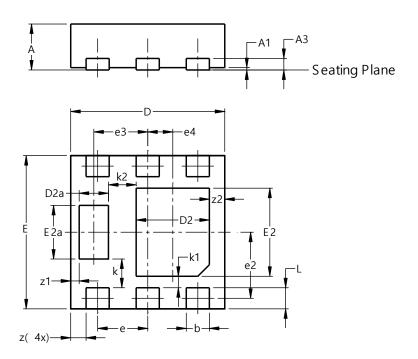






## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

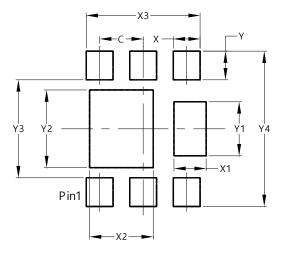


	U-DFN2020-6								
	(Тур	be F)							
Dim	Min	Max	Тур						
Α	0.57	0.63	0.60						
A1	0.00	0.05	0.03						
A3	-	-	0.15						
b	0.25	0.35	0.30						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
D2a	0.33	0.43	0.38						
Е	1.95	2.05	2.00						
E2	1.05	1.25	1.15						
E2a	0.65	0.75	0.70						
е		0.65 BS	С						
e2	C	).863 BS	SC						
e3		0.70 BS	-						
e4	C	).325 BS	SC						
k		0.37 BS	С						
k1		0.15 BS	С						
k2		0.36 BS	С						
L	0.225 0.325 0.275								
z		0.20 BSC							
z1	-	).110 BS	-						
z2		0.20 BS	С						
All D	Dimens	ions in	mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
X3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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